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Details

E·XFI

Product Status	Active
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	I ² C, SCI
Peripherals	LED, LVD, POR, PWM
Number of I/O	26
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc908jl16cfje

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

MCU Block Diagram



NOTES:

- 1. Shared pin: OSC2/RCCLK/PTA6/KBI6
- 2. Pin contains integrated pull-up device
- 3. Pin contains programmable pull-up device
- 4. LED direct sink pin
- 5. 25-mA output drive pin
- 6. Pin is open-drain output when MMIIC function enabled;
- position of SDA and SCL are selected in CONFIG2 register.
- 7. Pins available on 32-pin packages only

Figure 1-1. MC68HC908JL16 Block Diagram



General Description

Pin Name	Pin Description	Input/Output	Voltage Level				
	ADC12: channel-12 input of ADC	2: channel-12 input of ADC Input V _{SS}					
ADC12/12CLK	T2CLK: external input clock for TIM2	Input	V _{DD}				
	8-bit general-purpose I/O port	Input/output	V _{DD}				
	Each pin has programmable internal pull up when configured as input	Input	V _{DD}				
	Pins as keyboard interrupts, KBI0–KBI7	Input	V _{DD}				
PTA0-PTA7	PTA0–PTA5 and PTA7 have LED direct sink capability	Output	V _{DD}				
	PTA6 as OSC2/RCCLK	Output	V _{DD}				
	PTA2 as SDA of MMIIC		V _{SS} to V _{DD} (open-drain)				
	PTA3 as SCL of MMIIC	Input/output	V _{SS} to V _{DD} (open-drain)				
	8-bit general-purpose I/O port	Input/output	V _{DD}				
FIBO-FIB/	Pins as ADC input channels, ADC0-ADC7	Input	$\rm V_{SS}$ to $\rm V_{DD}$				
	8-bit general purpose I/O port; with programmable internal pull ups on PTD6–PTD7	Input/output	V _{DD}				
	PTD0-PTD3 as ADC input channels, ADC11-ADC8	Input	$\rm V_{SS}$ to $\rm V_{DD}$				
	PTD2–PTD3 and PTD6–PTD7 have LED direct sink capability	Output	VSS				
	PTD4 as T1CH0 of TIM1	Input/output	V _{DD}				
	PTD5 as T1CH1 of TIM1	Input/output	V _{DD}				
PTD0-PTD7	PTD6–PTD7 have configurable 25-mA open-drain output	Output	V_{SS}				
	PTD6 as TxD of SCI	Output	V _{DD}				
	PTD7 as RxD of SCI	Input	V _{DD}				
	PTD6 as SCL of MMIIC	Input/output	V _{SS} to V _{DD} (open-drain)				
	PTD7 as SDA of MMIIC	Input/output	V _{SS} to V _{DD} (open-drain)				
	2-bit general-purpose I/O port	Input/output	V _{DD}				
PTE0-PTE1	PTE0 as T2CH0 of TIM2	Input/output	V _{DD}				
	PTE1 as T2CH1 of TIM2	Input/output	V _{DD}				

Table 1-1. Pin Functions (Continued)

NOTE

Devices in 28-pin packages, the following pins are not available: PTA7/KBI7, PTE0/T2CH0, PTE1/T2CH1, and ADC12/T2CLK.



Memory

\$0000 ↓	I/O REGISTERS
\$0045	70 61123
\$0046	RESERVED
↓ \$005E	26 BYTES
\$0060	
\downarrow	RAM 512 RVTES
\$025F	512 01 123
\$0260	UNIMPLEMENTED
↓ \$BBFF	47,520 BYTES
\$BC00	
↓2000	
\$FBFF	10,304 D11E3
\$FC00	MONITOR ROM
↓ \$EDEE	512 BYTES
\$FE00	BREAK STATUS REGISTER (BSR)
\$FE01	RESET STATUS REGISTER (RSR)
\$FE02	RESERVED
\$FE03	BREAK FLAG CONTROL REGISTER (BFCR)
\$FE04	INTERRUPT STATUS REGISTER 1 (INT1)
\$FE05	INTERRUPT STATUS REGISTER 2 (INT2)
\$FE06	INTERRUPT STATUS REGISTER 3 (INT3)
\$FE07	RESERVED
\$FE08	FLASH CONTROL REGISTER (FLCR)
\$FE09	
	RESERVED
¢EE0C	
\$FE0E	BREAK STATUS AND CONTROL BEGISTER (BRKSCB)
\$FE0E	BESERVED
\$FE10	HEOLINED
\downarrow	MONITOR ROM
\$FFCE	447 BTTE3
\$FFCF	FLASH BLOCK PROTECT REGISTER (FLBPR)
\$FFD0	MASK OPTION REGISTER (MOR)
\$FFD1	RESERVED
↓ \$FFDB	11 BYTES
\$FFDC	
↓	USER FLASH VECTORS
\$FFFF	0001100

Figure 2-1. Memory Map



I/O Section

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
\$0000	Port A Data Register (PTA)	Read: Write:	PTA7	PTA6	PTA5	PTA4	PTA3	PTA2	PTA1	PTA0
	(1779	Reset:				Unaffecte	d by reset			
\$0001	Port B Data Register (PTB)	Read: Write:	PTB7	PTB6	PTB5	PTB4	PTB3	PTB2	PTB1	PTB0
	()	Reset:				Unaffecte	d by reset			
\$0002	Unimplemented	Read: Write:								
		r			1					
\$0003	Port D Data Register (PTD)	Read: Write:	PTD7	PTD6	PTD5	PTD4	PTD3	PTD2	PTD1	PTD0
		Reset:			_	Unaffecte	d by reset			
\$0004	Data Direction Register A (DDRA)	Read: Write:	DDRA7	DDRA6	DDRA5	DDRA4	DDRA3	DDRA2	DDRA1	DDRA0
	(,	Reset:	0	0	0	0	0	0	0	0
\$0005	Data Direction Register B (DDRB)	Read: Write:	DDRB7	DDRB6	DDRB5	DDRB4	DDRB3	DDRB2	DDRB1	DDRB0
	()	Reset:	0	0	0	0	0	0	0	0
\$0006	Unimplemented	l								
		ſ		Γ	1					
\$0007	Data Direction Register D (DDRD)	Read: Write:	DDRD7	DDRD6	DDRD5	DDRD4	DDRD3	DDRD2	DDRD1	DDRD0
		Reset:	0	0	0	0	0	0	0	0
	Port E Data Register	Read:							PTE1	PTE0
\$0008	(PTE)	Write:				L la effe et e				
\$0000	Unimplemented	Reset:				Unanecte	d by reset			
ψ0009	Onimplemented	l								
		Read:	0	0	0	0				
\$000A	Port D Control Register	Write:					SLOWD7	SLOWD6	PTDPU7	PTDPU6
	(PDCR)	Reset:	0	0	0	0	0	0	0	0
\$000B	Unimplemented	[
	Data Direction Register F	Read:							DDRE1	DDRE0
\$000C	(DDRE)	Write:						-		-
		Reset:	0	0	0	0	0	0	0	0
	U = Unaffected		x = indeterm	linate		= Unimplem	entea	К	= Heserved	

Figure 2-2. Control, Status, and Data Registers (Sheet 1 of 7)



Memory

2.5.2 FLASH Control Register

The FLASH control register (FCLR) controls FLASH program and erase operations.



Figure 2-3. FLASH Control Register (FLCR)

HVEN — High Voltage Enable Bit

This read/write bit enables the charge pump to drive high voltages for program and erase operations in the array. HVEN can only be set if either PGM = 1 or ERASE = 1 and the proper sequence for program or erase is followed.

1 = High voltage enabled to array and charge pump on

0 = High voltage disabled to array and charge pump off

MASS — Mass Erase Control Bit

This read/write bit configures the memory for mass erase operation or page erase operation when the ERASE bit is set.

1 = Mass erase operation selected

0 = Page erase operation selected

ERASE — Erase Control Bit

This read/write bit configures the memory for erase operation. ERASE is interlocked with the PGM bit such that both bits cannot be equal to 1 or set to 1 at the same time.

1 = Erase operation selected

0 = Erase operation not selected

PGM — Program Control Bit

This read/write bit configures the memory for program operation. PGM is interlocked with the ERASE bit such that both bits cannot be equal to 1 or set to 1 at the same time.

1 = Program operation selected

0 = Program operation not selected





6.4.3.1 Unbuffered Output Compare

Any output compare channel can generate unbuffered output compare pulses as described in 6.4.3 Output Compare. The pulses are unbuffered because changing the output compare value requires writing the new value over the old value currently in the TIM channel registers.

An unsynchronized write to the TIM channel registers to change an output compare value could cause incorrect operation for up to two counter overflow periods. For example, writing a new value before the counter reaches the old value but after the counter reaches the new value prevents any compare during that counter overflow period. Also, using a TIM overflow interrupt routine to write a new, smaller output compare value may cause the compare to be missed. The TIM may pass the new value before it is written.

Use the following methods to synchronize unbuffered changes in the output compare value on channel x:

- When changing to a smaller value, enable channel x output compare interrupts and write the new value in the output compare interrupt routine. The output compare interrupt occurs at the end of the current output compare pulse. The interrupt routine has until the end of the counter overflow period to write the new value.
- When changing to a larger output compare value, enable TIM overflow interrupts and write the new
 value in the TIM overflow interrupt routine. The TIM overflow interrupt occurs at the end of the
 current counter overflow period. Writing a larger value in an output compare interrupt routine (at
 the end of the current pulse) could cause two output compares to occur in the same counter
 overflow period.

6.4.3.2 Buffered Output Compare

Channels 0 and 1 can be linked to form a buffered output compare channel whose output appears on the TCH0 pin. The TIM channel registers of the linked pair alternately control the output.

Setting the MS0B bit in TIM channel 0 status and control register (TSC0) links channel 0 and channel 1. The output compare value in the TIM channel 0 registers initially controls the output on the TCH0 pin. Writing to the TIM channel 1 registers enables the TIM channel 1 registers to synchronously control the output after the TIM overflows. At each subsequent overflow, the TIM channel registers (0 or 1) that control the output are the ones written to last. TSC0 controls and monitors the buffered output compare function, and TIM channel 1 status and control register (TSC1) is unused. While the MS0B bit is set, the channel 1 pin, TCH1, is available as a general-purpose I/O pin.

NOTE

In buffered output compare operation, do not write new output compare values to the currently active channel registers. User software should track the currently active channel to prevent writing a new value to the active channel. Writing to the active channel registers is the same as generating unbuffered output compares.

6.4.4 Pulse Width Modulation (PWM)

By using the toggle-on-overflow feature with an output compare channel, the TIM can generate a PWM signal. The value in the TIM counter modulo registers determines the period of the PWM signal. The channel pin toggles when the counter reaches the value in the TIM counter modulo registers. The time between overflows is the period of the PWM signal.

As Figure 6-3 shows, the output compare value in the TIM channel registers determines the pulse width of the PWM signal. The time between overflow and output compare is the pulse width. Program the TIM



Timer Interface Module (TIM)

6.9.3 TIM Counter Modulo Registers

The read/write TIM modulo registers contain the modulo value for the TIM counter. When the TIM counter reaches the modulo value, the overflow flag (TOF) becomes set, and the TIM counter resumes counting from \$0000 at the next timer clock. Writing to the high byte (TMODH) inhibits the TOF bit and overflow interrupts until the low byte (TMODL) is written. Reset sets the TIM counter modulo registers.







	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	Bit 7	6	5	4	3	2	1	Bit 0
Reset:	1	1	1	1	1	1	1	1

Figure 6-8. TIM Counter Modulo Register Low (TMODL)



6.9.4 TIM Channel Status and Control Registers

Each of the TIM channel status and control registers:

- Flags input captures and output compares
- Enables input capture and output compare interrupts
- Selects input capture, output compare, or PWM operation
- Selects high, low, or toggling output on output compare
- Selects rising edge, falling edge, or any edge as the active input capture trigger
- Selects output toggling on TIM overflow
- Selects 0% and 100% PWM duty cycle
- Selects buffered or unbuffered output compare/PWM operation



Figure 6-9. TIM Channel 0 Status and Control Register (TSC0)





Figure 6-11. CHxMAX Latency

6.9.5 TIM Channel Registers

These read/write registers contain the captured TIM counter value of the input capture function or the output compare value of the output compare function. The state of the TIM channel registers after reset is unknown.

In input capture mode (MSxB:MSxA = 0:0), reading the high byte of the TIM channel x registers (TCHxH) inhibits input captures until the low byte (TCHxL) is read.

In output compare mode (MSxB:MSxA \neq 0:0), writing to the high byte of the TIM channel x registers (TCHxH) inhibits output compares until the low byte (TCHxL) is written.

Address: T1CH0H, \$0026 and T2CH0H, \$0036

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	Bit 15	14	13	12	11	10	9	Bit 8
Reset:				Indeterminat	e after reset			

Figure 6-12. TIM Channel 0 Register High (TCH0H)



Figure 6-13. TIM Channel 0 Register Low (TCH0L)









7.4.2.1 Character Length

The transmitter can accommodate either 8-bit or 9-bit data. The state of the M bit in SCI control register 1 (SCC1) determines character length. When transmitting 9-bit data, bit T8 in SCI control register 3 (SCC3) is the ninth bit (bit 8).

7.4.2.2 Character Transmission

During an SCI transmission, the transmit shift register shifts a character out to the TxD pin. The SCI data register (SCDR) is the write-only buffer between the internal data bus and the transmit shift register. To initiate an SCI transmission:

- 1. Enable the SCI by writing a logic 1 to the enable SCI bit (ENSCI) in SCI control register 1 (SCC1).
- 2. Enable the transmitter by writing a logic 1 to the transmitter enable bit (TE) in SCI control register 2 (SCC2).
- 3. Clear the SCI transmitter empty bit by first reading SCI status register 1 (SCS1) and then writing to the SCDR.
- 4. Repeat step 3 for each subsequent transmission.

At the start of a transmission, transmitter control logic automatically loads the transmit shift register with a preamble of logic 1s. After the preamble shifts out, control logic transfers the SCDR data into the transmit shift register. A logic 0 start bit automatically goes into the least significant bit position of the transmit shift register. A logic 1 stop bit goes into the most significant bit position.

The SCI transmitter empty bit, SCTE, in SCS1 becomes set when the SCDR transfers a byte to the transmit shift register. The SCTE bit indicates that the SCDR can accept new data from the internal data bus. If the SCI transmit interrupt enable bit, SCTIE, in SCC2 is also set, the SCTE bit generates a transmitter CPU interrupt request.

When the transmit shift register is not transmitting a character, the TxD pin goes to the idle condition, logic 1. If at any time software clears the ENSCI bit in SCI control register 1 (SCC1), the transmitter and receiver relinquish control of the port pin.

7.4.2.3 Break Characters

Writing a logic 1 to the send break bit, SBK, in SCC2 loads the transmit shift register with a break character. A break character contains all logic 0s and has no start, stop, or parity bit. Break character length depends on the M bit in SCC1. As long as SBK is at logic 1, transmitter logic continuously loads break characters into the transmit shift register. After software clears the SBK bit, the shift register finishes transmitting the last break character and then transmits at least one logic 1. The automatic logic 1 at the end of a break character guarantees the recognition of the start bit of the next character.

The SCI recognizes a break character when a start bit is followed by eight or nine logic 0 data bits and a logic 0 where the stop bit should be.

Receiving a break character has these effects on SCI registers:

- Sets the framing error bit (FE) in SCS1
- Sets the SCI receiver full bit (SCRF) in SCS1
- Clears the SCI data register (SCDR)
- Clears the R8 bit in SCC3
- Sets the break flag bit (BKF) in SCS2
- May set the overrun (OR), noise flag (NF), parity error (PE), or reception in progress flag (RPF) bits



Serial Communications Interface (SCI)

7.4.2.4 Idle Characters

An idle character contains all logic 1s and has no start, stop, or parity bit. Idle character length depends on the M bit in SCC1. The preamble is a synchronizing idle character that begins every transmission.

If the TE bit is cleared during a transmission, the TxD pin becomes idle after completion of the transmission in progress. Clearing and then setting the TE bit during a transmission queues an idle character to be sent after the character currently being transmitted.

NOTE

When queueing an idle character, return the TE bit to logic 1 before the stop bit of the current character shifts out to the TxD pin. Setting TE after the stop bit appears on TxD causes data previously written to the SCDR to be lost. Toggle the TE bit for a queued idle character when the SCTE bit becomes set and just before writing the next byte to the SCDR.

7.4.2.5 Inversion of Transmitted Output

The transmit inversion bit (TXINV) in SCI control register 1 (SCC1) reverses the polarity of transmitted data. All transmitted values, including idle, break, start, and stop bits, are inverted when TXINV is at logic 1. (See 7.8.1 SCI Control Register 1.)

7.4.2.6 Transmitter Interrupts

These conditions can generate CPU interrupt requests from the SCI transmitter:

- SCI transmitter empty (SCTE) The SCTE bit in SCS1 indicates that the SCDR has transferred a character to the transmit shift register. SCTE can generate a transmitter CPU interrupt request. Setting the SCI transmit interrupt enable bit, SCTIE, in SCC2 enables the SCTE bit to generate transmitter CPU interrupt requests.
- Transmission complete (TC) The TC bit in SCS1 indicates that the transmit shift register and the SCDR are empty and that no break or idle character has been generated. The transmission complete interrupt enable bit, TCIE, in SCC2 enables the TC bit to generate transmitter CPU interrupt requests.

7.4.3 Receiver

Figure 7-5 shows the structure of the SCI receiver.

7.4.3.1 Character Length

The receiver can accommodate either 8-bit or 9-bit data. The state of the M bit in SCI control register 1 (SCC1) determines character length. When receiving 9-bit data, bit R8 in SCI control register 2 (SCC2) is the ninth bit (bit 8). When receiving 8-bit data, bit R8 is a copy of the eighth bit (bit 7).

7.4.3.2 Character Reception

During an SCI reception, the receive shift register shifts characters in from the RxD pin. The SCI data register (SCDR) is the read-only buffer between the internal data bus and the receive shift register.

After a complete character shifts into the receive shift register, the data portion of the character transfers to the SCDR. The SCI receiver full bit, SCRF, in SCI status register 1 (SCS1) becomes set, indicating that the received byte can be read. If the SCI receive interrupt enable bit, SCRIE, in SCC2 is also set, the SCRF bit generates a receiver CPU interrupt request.

To determine the value of a data bit and to detect noise, recovery logic takes samples at RT8, RT9, and RT10. Table 7-3 summarizes the results of the data bit samples.

RT8, RT9, and RT10 Samples	Data Bit Determination	Noise Flag
000	0	0
001	0	1
010	0	1
011	1	1
100	0	1
101	1	1
110	1	1
111	1	0

Table 7-3. Data Bit Recovery

NOTE

The RT8, RT9, and RT10 samples do not affect start bit verification. If any or all of the RT8, RT9, and RT10 start bit samples are logic 1s following a successful start bit verification, the noise flag (NF) is set and the receiver assumes that the bit is a start bit.

To verify a stop bit and to detect noise, recovery logic takes samples at RT8, RT9, and RT10. Table 7-4 summarizes the results of the stop bit samples.

RT8, RT9, and RT10 Samples	Framing Error Flag	Noise Flag
000	1	0
001	1	1
010	1	1
011	0	1
100	1	1
101	0	1
110	0	1
111	0	0

Table 7-4. Stop Bit Recovery

7.4.3.4 Framing Errors

If the data recovery logic does not detect a logic 1 where the stop bit should be in an incoming character, it sets the framing error bit, FE, in SCS1. A break character also sets the FE bit because a break character has no stop bit. The FE bit is set at the same time that the SCRF bit is set.



Serial Communications Interface (SCI)

SCP1 and SCP0	Prescaler Divisor (PD)	SCR2, SCR1, and SCR0	Baud Rate Divisor (BD)	Baud Rate (BUS CLOCK= 4.9152 MHz)	
00	1	000	1	76,800	
00	1	001	2	38,400	
00	1	010	4	19,200	
00	1	011	8	9,600	
00	1	100	16	4,800	
00	1	101	32	2,400	
00	1	110	64	1,200	
00	1	111	128	600	
01	3	000	1	25,600	
01	3	001	2	12,800	
01	3	010	4	6,400	
01	3	011	8	3,200	
01	3	100	16	1,600	
01	3	101	32	800	
01	3	110	64	400	
01	3	111	128	200	
10	4	000	1	19,200	
10	4	001	2	9,600	
10	4	010	4	4,800	
10	4	011	8	2,400	
10	4	100	16	1,200	
10	4	101	32	600	
10	4	110	64	300	
10	4	111	128	150	
11	13	000	1	5,908	
11	13	001	2	2,954	
11	13	010	4	1,477	
11	13	011	8	739	
11	13	100	16	369	
11	13	101	32	185	
11	13	110	64	92	
11	13	111	128	46	

Table 7-8. SCI Baud Rate Selection Examples



External Interrupt (IRQ)

The vector fetch or software clear may occur before or after the interrupt pin returns to logic one. As long as the pin is low, the interrupt request remains pending. A reset will clear the latch and the MODE control bit, thereby clearing the interrupt even if the pin stays low.

When set, the IMASK bit in the INTSCR mask all external interrupt requests. A latched interrupt request is not presented to the interrupt priority logic unless the IMASK bit is clear.

NOTE The interrupt mask (I) in the condition code register (CCR) masks all interrupt requests, including external interrupt requests. (See 4.5 Exception Control.)



Figure 11-1. IRQ Module Block Diagram

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
	IRQ Status and Control	Read:	0	0	0	0	IRQF	0	IMASK	MODE
\$001D Register		Write:						ACK	IWAGA	WODL
	(INTSCR)	Reset:	0	0	0	0	0	0	0	0
				= Unimplem	ented					

Figure 11-2. IRQ I/O Register Summary



The vector fetch or software clear and the return of all enabled keyboard interrupt pins to logic 1 may occur in any order.

If the MODEK bit is clear, the keyboard interrupt pin is falling-edge-sensitive only. With MODEK clear, a vector fetch or software clear immediately clears the keyboard interrupt request.

Reset clears the keyboard interrupt request and the MODEK bit, clearing the interrupt request even if a keyboard interrupt pin stays at logic 0.

The keyboard flag bit (KEYF) in the keyboard status and control register can be used to see if a pending interrupt exists. The KEYF bit is not affected by the keyboard interrupt mask bit (IMASKK) which makes it useful in applications where polling is preferred.

To determine the logic level on a keyboard interrupt pin, disable the pull-up device, use the data direction register to configure the pin as an input and then read the data register.

NOTE

Setting a keyboard interrupt enable bit (KBIEx) forces the corresponding keyboard interrupt pin to be an input, overriding the data direction register. However, the data direction register bit must be a logic 0 for software to read the pin.

12.4.1 Keyboard Initialization

When a keyboard interrupt pin is enabled, it takes time for the internal pull-up to reach a logic 1. Therefore a false interrupt can occur as soon as the pin is enabled.

To prevent a false interrupt on keyboard initialization:

- 1. Mask keyboard interrupts by setting the IMASKK bit in the keyboard status and control register.
- 2. Enable the KBI pins by setting the appropriate KBIEx bits in the keyboard interrupt enable register.
- 3. Write to the ACKK bit in the keyboard status and control register to clear any false interrupts.
- 4. Clear the IMASKK bit.

An interrupt signal on an edge-triggered pin can be acknowledged immediately after enabling the pin. An interrupt signal on an edge- and level-triggered interrupt pin must be acknowledged after a delay that depends on the external load.

Another way to avoid a false interrupt:

- 1. Configure the keyboard pins as outputs by setting the appropriate DDRA bits in the data direction register A.
- 2. Write logic 1's to the appropriate port A data register bits.
- 3. Enable the KBI pins by setting the appropriate KBIEx bits in the keyboard interrupt enable register.

12.5 Keyboard Interrupt Registers

Two registers control the operation of the keyboard interrupt module:

- Keyboard status and control register
- Keyboard interrupt enable register



16.2.3 CPU During Break Interrupts

The CPU starts a break interrupt by:

- Loading the instruction register with the SWI instruction
- Loading the program counter with \$FFFC:\$FFFD (\$FEFC:\$FEFD in monitor mode)

The break interrupt begins after completion of the CPU instruction in progress. If the break address register match occurs on the last cycle of a CPU instruction, the break interrupt begins immediately.

16.2.4 TIM During Break Interrupts

A break interrupt stops the timer counter.

16.2.5 COP During Break Interrupts

The COP is disabled during a break interrupt when V_{TST} is present on the \overline{RST} pin.

16.2.6 Break Module Registers

These registers control and monitor operation of the break module:

- Break status and control register (BRKSCR)
- Break address register high (BRKH)
- Break address register low (BRKL)
- Break status register (BSR)
- Break flag control register (BFCR)

16.2.6.1 Break Status and Control Register (BRKSCR)

The break status and control register contains break module enable and status bits.



Figure 16-3. Break Status and Control Register (BRKSCR)

BRKE — Break Enable Bit

This read/write bit enables breaks on break address register matches. Clear BRKE by writing a logic zero to bit 7. Reset clears the BRKE bit.

- 1 = Breaks enabled on 16-bit address match
- 0 = Breaks disabled

BRKA — Break Active Bit

This read/write status and control bit is set when a break address match occurs. Writing a logic one to BRKA generates a break interrupt. Clear BRKA by writing a logic zero to it before exiting the break routine. Reset clears the BRKA bit.

- 1 = Break address match
- 0 = No break address match



start of boundary address (the page start address: \$XX00, \$XX40, \$XX80, or \$00C0) and DATASIZE must be the same size when accessing the same page.

In some applications, the user may want to repeatedly store and read a set of data from an area of non-volatile memory. This can be easily implemented when EEPROM memory is used because the byte erase is allowed in EEPROM. On the other hand in FLASH memory, a minimum erase size is a page (64 bytes), so unused locations in a page will be wasted when it is used for data storage.

The EE_WRITE routine is designed to emulate EEPROM using FLASH. This allows a FLASH page to implement data storage more efficiently. Each call of the EE_WRITE routine will automatically transfer the data in the data array (in RAM) to the next available blank locations in a page. Once the page is filled up with data, the EE_WRITE routine automatically erases the page and programs updated data in the same page. In a FLASH page, data is programmed to FLASH with in a block that consists of the data array and one boundary byte. The boundary byte contains the remaining number of bytes which can be programmed in the page (see Figure 16-16).



Figure 16-16. EE_WRITE FLASH Memory Usage

When using this routine to store a 3-byte data array, the FLASH page can be programmed 16 times before the an erase is required. In effect, the write/erase endurance is increased by 16 times. When a 15-byte data array is used, the write/erase endurance is increased by 4 times. Due to the FLASH page size limitation, the data array is limited from 2 bytes to 15 bytes.

The coding example below uses the \$EF00-\$EE3F page for data storage. The data array size is 15 bytes, and the bus speed is 4.9152 MHz. The coding assumes the data block is already loaded in RAM, with the address pointer, FILE_PTR, pointing to the first byte of the data block.



Development Support

		ORG	RAM		
		:			
FILE_P7	rr:				
BUS_SPI)	DS.B	1	;	Indicates 4x bus frequency
DATASIZ	ZE	DS.B	1	;	Data size to be programmed
START_A	ADDR	DS.W	1	;	FLASH page start address
DATAARF	YAS	DS.B	15	;	Reserved data array
EE_WRI1	ΓE	EQU	\$FD3F		
FLASH_S	START	EQU	\$EF00		
		ORG	FLASH		
INITIAI	LISATION	1:			
	MOV	#20,BUS_	SPD		
	MOV	#15,DATA	SIZE		
	LDHX	#FLASH_S	START		
	STHX	START_AD	DR		
	RTS				
MAIN:					
	BSR	INITIALI	SATION	ſ	
	:				
	:				
	LHDX	#FILE_PI	'R		
	JSR	EE_WRITE	1		

NOTE

The EE_WRITE routine is unable to check for incorrect data blocks, such as the FLASH page boundary address and data size. It is the responsibility of the user to ensure the starting address indicated in the data block is at the FLASH page boundary and the data size is 2 to 15. When the EE_WRITE routine detects a different data size from the size set up in the previous operation, the operation will not be executed. However in some situations, the routine cannot detect incorrect data size. The user must ensure that data size is same as the previous operation whenever this routine is executed.



Chapter 17 Electrical Specifications

17.1 Introduction

This section contains electrical and timing specifications.

17.2 Absolute Maximum Ratings

Maximum ratings are the extreme limits to which the microcontroller unit (MCU) can be exposed without permanently damaging it.

NOTE

This device is not guaranteed to operate properly at the maximum ratings. Refer to 17.5 5-V DC Electrical Characteristics and 17.8 3-V DC Electrical Characteristics for guaranteed operating conditions.

Table 17-1. Absolute Maximum Ratings

Characteristic ⁽¹⁾	Symbol	Value	Unit
Supply voltage	V _{DD}	-0.3 to +6.0	V
Input voltage	V _{IN}	V_{SS} –0.3 to V_{DD} +0.3	V
Mode entry voltage, IRQ pin	V _{TST}	V _{SS} -0.3 to +8.5	V
Maximum current per pin $$ excluding V_{DD} and V_{SS}	I	±25	mA
Storage temperature	T _{STG}	-55 to +150	°C
Maximum current out of V _{SS}	I _{MVSS}	100	mA
Maximum current into V _{DD}	I _{MVDD}	100	mA

1. Voltages referenced to V_{SS} .

NOTE

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum-rated voltages to this high-impedance circuit. For proper operation, it is recommended that V_{IN} and V_{OUT} be constrained to the range $V_{SS} \leq (V_{IN} \text{ or } V_{OUT}) \leq V_{DD}$. Reliability of operation is enhanced if unused inputs are connected to an appropriate logic voltage level (for example, either V_{SS} or V_{DD} .)



ADC10 Characteristics

Characteristic	Conditions	Symbol	Min	Typ ⁽¹⁾	Мах	Unit	Comment
Analog source impedance		R _{AS}	_	_	10	kΩ	External to MCU
Ideal resolution (1 LSB)	10-bit mode		1.758	5	5.371	mV	V _{REFH} /2 ^N
	8-bit mode	neo	7.031	20	21.48		
Total unadjusted error	10-bit mode	Ц	0	±2.0	±2.5	LSB	Includes quantization
	8-bit mode	LTUE	0	±0.7	±1.0		
Differential non-linearity	10-bit mode		0	±0.5	—	LSB	
	8-bit mode	DINL	0	±0.3	—		
	Monotonicity and no-missing-codes guaranteed						
Integral non-linearity	10-bit mode	INL	0	±0.5	_	LSB	
	8-bit mode		0	±0.3	—		
Zero-scale error	10-bit mode	E _{ZS}	0	±0.5	—	LSB	$V_{ADIN} = V_{SS}$
	8-bit mode		0	±0.3	—		
Full-scale error	10-bit mode	E _{FS}	0	±2.0	—	LSB	$V_{ADIN} = V_{DD}$
	8-bit mode		0	±0.3	_		
Quantization error	10-bit mode	E _Q	_	_	±0.5	LSB	8-bit mode is not truncated
	8-bit mode		_	_	±0.5		
Input leakage error	10-bit mode	E.	0	±0.2	±5	LSB	Pad leakage ⁽⁴⁾ * R _{AS}
	8-bit mode		0	±0.1	±1.2		
Bandgap voltage input ⁽⁵⁾		V _{BG}	1.17	1.245	1.32	V	

Table 17-11. ADC10 Characteristics

Typical values assume V_{DD} = 5.0 V, temperature = 25°C, f_{ADCK} = 1.0 MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
 Incremental I_{DD} added to MCU mode current.

3. Values are based on characterization results, not tested in production.

4. Based on typical input pad leakage current.

5. LVI must be enabled, (LVID = 0, in CONFIG1). Voltage input to ADCH4:0 = \$1A, an ADC conversion on this channel allows user to determine supply voltage.







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32 LEAD, 0.8 PITCH (7 X	STANDARD: JEDEC MS-026 BBA				